

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A semiconductor package comprising:
 - a chip carrier including a grounded pad on a first side of said chip carrier;
 - a semiconductor chip coupled to said first side of said chip carrier;
 - a conductive lid substantially coplanar with said first side of said chip carrierthermally coupled to said semiconductor chip; and
 - a conductive structure electrically coupled to said grounded pad and to said conductive lid.
2. (Original) The semiconductor package of claim 1 wherein a solder connects said conductive structure and said grounded pad.
3. (Original) The semiconductor package according to claim 1 wherein said conductive structure is electrically coupled to said grounded pad with an electrically conductive adhesive material.
4. (Original) The semiconductor package according to claim 1 wherein said conductive structure is electrically coupled to said conductive lid with an electrically conductive adhesive material.
5. (Original) The semiconductor package according to claim 1 wherein said conductive structure is coupled to said chip carrier using an electrically insulative adhesive material.
6. (Original) The semiconductor package according to claim 1 wherein said conductive structure is coupled to said chip carrier using a thermally conductive adhesive material.
7. (Original) The semiconductor package according to claim 1 wherein said conductive structure comprises a spring.

8. (Original) The semiconductor package according to claim 1 wherein said conductive structure comprises a block.
9. (Currently Amended) The semiconductor package according to claim 1 wherein said ~~conductive structure block~~ comprises a surface mount technology (SMT) discrete component.
10. (Currently Amended) The semiconductor package according to claim 1 wherein a solder couples said conductive structure to said grounded pad;
an electrically conductive adhesive material couples said conductive structure to said conductive lid; and
an electrically insulative adhesive material couples said conductive structure to said [the] chip carrier.
11. (Original) The semiconductor package according to claim 10 wherein said conductive structure comprises a conductive spring.
12. (Original) The semiconductor package according to claim 10 wherein said conductive structure comprises a block.
13. (Original) The semiconductor package according to claim 10 wherein said conductive structure comprises a surface mount technology (SMT) discrete component.
14. (Withdrawn) A method for manufacturing a semiconductor package, the semiconductor package including a chip carrier having a grounded pad, said method comprising the steps of:
applying a first electrically conductive adhesive material on said grounded pad;
providing a conductive structure coupled to said first electrically conductive adhesive material;
providing a semiconductor chip on said chip carrier;

applying a second electrically conductive adhesive material on said conductive structure;

applying electrically insulative adhesive material on said semiconductor chip; and providing a conductive lid coupled to said second electrically conductive adhesive material and said electrically insulative adhesive material.

15. (Withdrawn) The method according to claim 14 wherein said first electrically conductive adhesive material comprises solder.
16. (Withdrawn) The method according to claim 14 wherein said conductive structure comprises a conductive spring.
17. (Withdrawn) The method according to claim 14 wherein said conductive structure comprises a surface mount technology (SMT) discrete component.
18. (Withdrawn) The method according to claim 14 wherein said conductive structure comprises a conductive block.
19. (Withdrawn) The method according to claim 14 wherein the step of providing said conductive structure coupled to said first electrically conductive adhesive material comprises picking said conductive structure from a first location and placing said conductive structure on said first electrically conductive adhesive material.
20. (Withdrawn) The method according to claim 14 wherein the step of providing said semiconductor chip on said chip carrier comprises picking said semiconductor chip from a second location and placing said semiconductor chip on said chip carrier.
21. (New) The semiconductor package of claim 1 wherein the entire length of said conductive lid is substantially coplanar with said first side of said chip carrier.

22. (New) The semiconductor package of claim 1 wherein an end of said conductive lid extends beyond at least one side of said semiconductor chip.
23. (New) The semiconductor package of claim 1 wherein said conductive structure is located on said first side of said chip carrier.

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